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TI **Silver**-containing **solder** of low melting point  
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SO Jpn. Kokai Tokkyo Koho, 4 pp.  
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AB The **solder** (m. 330-420.degree.) contg. Ag 10-30, Sn 70-90, Cu, In, and/or Ga 0.05-5, and Fe and/or Ni 0.05-1% shows good wetting to Cu and Ni and develops the beads of tensile strength 9.5-20 kg/mm2, elongation 7-20%, shear strength 10-20 kg/mm2, and Vickers hardness 25-55.